

## Patent claims

1. Method, in which
  - a circuit carrier (3) is connected to a component (1) via contacts (2) which place the component (1) at a distance from the circuit carrier (3),
  - a foil (5) is applied to the component (1) and the circuit carrier (3),
  - the foil (5) is metallized.
2. Method according to Claim 1,
  - in which the metallization (6) of the foil (5) is electrically strengthened.
3. Method according to one of the previous claims in which a window (7) is opened up in the foil (5) on the side of the component (1) facing away from the circuit carrier (3).
4. Method according to one of the previous claims in which a contact element (8, 11), especially a solder bump, is placed on the circuit carrier (3).
5. Method according to Claim 4,
  - in which the contact element (11) is placed on the side of the circuit carrier (3) on which the component (1) is arranged and projects beyond the component (1).
6. Method according to one of the previous claims in which the component (1) is a high-frequency component, especially a very-high frequency component.
7. Method according to one of the previous claims in which a passive component (9) is arranged on the circuit carrier (3).
8. Method according to Claim 7,

in which the passive component (9) is arranged on the opposite side of the circuit carrier (3) to the component (1).

9. High frequency package,

which is manufactured in accordance with one of the Claims 1

5 to 8.